REMARKS

The specification has been amended to correct translation, typographical and idiomatic errors contained therein. No new matter has been added. The claims have been amended in order to more particularly point out and distinctly claim the subject matter which Applicants regard as the invention. Specifically speaking, Claims 1-8 have been canceled and replaced by newly presented Claims 17-21, which contain the subject matter of elected Claims 1-8. Newly presented Claims 22-29 contain the subject matter of non-elected Claims 9-16. No new matter has been added.

Claims 1-5, 7 and 8 have been rejected under 35 USC 102(b) as anticipated by Sano et al. Claim 6 has been rejected under 35 USC 103(a) as being unpatentable over Sano et al and further in view of Applicants' admissions. Applicants respectfully traverse these grounds of rejection and urge reconsideration in light of the following comments.

The presently claimed invention is directed to a plated resin molded article that has a metal plating layer provided on the surface of the thermoplastic resin molded article formed from a composition comprising: (A) 10 to 90 mass % of a matrix resin that has a water absorption after 24 hours in 23°C water, according to ISO62, of at least 0.6%; (B) 90 to 10 mass % of at least one resin selected from the group consisting of a polyolefin-based resin, a polyphenylene ether-based resin and a polyester-based resin; and at least one of (C) a water-soluble substance having a solubility at 25°C of not more than 300g in 100g water; (D) at least one of a surfactant and a coagulant; and (E) a phosphorus compound.

As discussed in the present specification, a plated resin molded article of the present invention exhibits a high adhesive strength between a thermoplastic resin molded article and a metal plating layer and has a beautiful appearance. These plated resin molded articles are provided by a treatment under mild conditions without the use of a heavy metal-

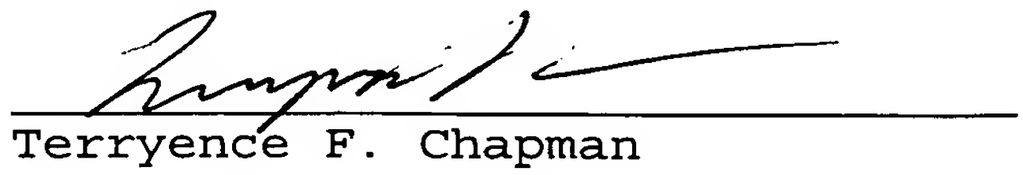
containing acid, such as chromic acid or potassium permanganate. As such, the present invention avoids the problems associated with conventional methods due to the environmental hazards associated with using a heavy metal etching treatment and yet still provides a highly adherent metal plating layer. It is respectfully submitted that the prior art cited by the Examiner does not disclose the presently claimed invention.

The Sano et al reference discloses a plated polyamide resin article formed from a polyamide resin composition comprising a polyamide resin, a polyphenylene ether resin, and a compatibilizer. However, this reference fails to disclose either of the water-soluble substance, at least one of a surfactant and a coagulant and a phosphorus compound required by the present claims. As such, this reference does not even make a showing of prima facie obviousness under 35 USC 103(a) with respect to the presently claimed invention. With respect to Applicants' so-called admission, although some phosphorus compounds are known as being fire retardants and anti-oxidants, there is nothing in the prior art that would suggest that a superior plated resin molded article would be obtained by adding a phosphorus compound to the other specified components required in the present claims.

Although the Examiner has not made a proper showing of prima facie obviousness under 35 USC 103(a), Examples and Comparative Examples are presented in the specification which show the criticality of the presence of the claimed components in the instant invention. Examples 7-11 correspond to the presently claimed invention and, as shown in Table 1 of the present specification, these compositions resulted in an unexpectedly higher adhesive strength. This is clearly unexpected in light of the prior art cited by the Examiner and further establishes the patentability of the presently claimed

invention thereover. The Examiner is respectfully requested to reconsider the present application and to pass it to issue.

Respectfully submitted,



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